

**METHODS AND APPARATUS FOR WIRE BONDING WITH  
WIRE LENGTH ADJUSTMENT IN AN INTEGRATED CIRCUIT**

**Abstract**

An integrated circuit is wire bonded in a manner such that there is consistent RF performance  
5 from integrated circuit package to integrated circuit package. Bond distances within the integrated circuit are measured, each corresponding to a wire bond to be formed. An area under a hypothetical wire bond profile is calculated as a function of the bond distances, a baseline wire length, and a baseline loop height. A wire is bonded across a given one of the bond distances to form a given one of the wire bonds. A wire bond profile for the given wire bond is provided having an area thereunder  
10 that is substantially equal to the calculated area.